



제 31회 한국반도체학술대회

The 31st Korean Conference on Semiconductors

2024년 1월 24일(수)-26일(금) | 경주화백컨벤션센터(HICO)

2024년 1월 25일(목), 15:30-17:15

Room J(204), 2층

A. Interconnect & Package 분과

[TJ3-A] Hybrid Bonding Technology

좌장: 이태익 선임(한국생산기술연구원), 이은호 교수(성균관대학교)

TJ3-A-1 15:30-15:45	Novel Method of Direct Cu Bonding Using Chemical Reducing Agents Jeehoo Na ^{1,2} , Eunhye Lee ¹ , So Jeong Lee ¹ , Dongwoo Lee ² , and Tae-Ik Lee ¹ ¹ Micro-Joining Center, Joining R&D Group, KITECH, ² Applied Mechanics and Materials Design Lab, School of Mechanical Engineering, Sungkyunkwan University
TJ3-A-2 15:45-16:00	Study on Employment of Au Film for Cu-Cu Low Temperature Bonding Ha-Hyung Pin ¹ , Hyun-Dong Lee ¹ , Hoon Choi ¹ , Ju-Hyeon Kim ³ , and Hoo-Jeong Lee ^{1,2,3} ¹ Department of Smart Fab. Technology, Sungkyunkwan University, ² Department of Advanced Materials Science & Engineering, Sungkyunkwan University, ³ Department of Semiconductor Convergence Engineering, Sungkyunkwan University
TJ3-A-3 16:00-16:15	하이브리드 본딩 기술 적용을 위한 저온 Cu-Cu 및 SiO ₂ -SiO ₂ 접합부의 정량적 계면접착에너지 평가 및 분석 권용범 ^{1,2} , 김가희 ^{1,2} , 김사라은경 ³ , 박영배 ^{1,2} ¹ 안동대학교 신소재공학부, ² 안동대학교 청정에너지소재기술연구센터, ³ 서울과학기술대학교 지능형반도체공학과
TJ3-A-4 16:15-16:30	구리/폴리머 하이브리드 본딩을 위한 화학적기계연마 기술 강석경 ¹ , 박주성 ² , 전찬수 ² , 김경민 ² , 김산하 ¹ ¹ Department of Mechanical Engineering, KAIST, ² Department of Material Science and Engineering, KAIST
TJ3-A-5 16:30-16:45	A Parametric Approach on HBM Hybrid Bonding Process Jae-Uk Lee ¹ , Sung-Hyun Oh ¹ , Sarah-Eunkyung Kim ² , Hoo-Jeong Lee ¹ , and Eun-Ho Lee ¹ ¹ Sungkyunkwan University, ² Seoul National University of Science of Technology
TJ3-A-6 16:45-17:00	Effect of Cu Pad Density on Cu/SiCN Hybrid Bonding: A Finite Element Analysis Study So-Yeon Park ¹ , Hyunji Yoon ¹ , Cha-Hee Kim ¹ , Sarah Eunkyung Kim ² , and Won-Jun Lee ¹ ¹ Department of Nanotechnology and Advanced Materials Engineering, Sejong University, ² Department of Semiconductor Engineering, Seoul National University of Science and Technology



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TJ3-A-7

17:00-17:45

Enhancing Si-bridge Performance: A Study on Signal Integrity and Structural Optimization

Ji Hoon Kang and Kee-Won Kwon

Department of Semiconductor Convergence Engineering, Sungkyunkwan University